

EIE 3118 pH 5.5 Aqua Flux

DESCRIPTION

EIE 3118 is a near neutral pH 5.5 organic halide-activated acid water-soluble flux specifically designed to improve productivity and to meet or exceeds ionic contamination cleanliness level specified by MIL-P-28809 requirement. This formula is specifically tailored to enhance good wetting for OSP treated bared copper PC boards when most Neutral pH fluxes will not perform effectively. The flux is also suited for SMOBC boards. EIE 3118 has no offensive odour and does not fume excessively during wave-soldering. The post-soldering residue is minimal and very soluble in water. This formulation does not generate excessive foaming problems during post-washing operation, commonly encountered with others commercially available neutral pH flux.

APPLICATION

EIE 3118 is effective in soldering bare-copper, HASL, nickel-plated and solder-plated boards assemblies. The flux can be applied by foaming, dipping and waving method. No saponifiers, neutralizers or detergents are necessary to be added in the post-wash compartment to aid removal of flux residue. The wash and rinse water is near neutral and biodegradable making disposal directly down the drain possible. Post-residue from EIE 3118 flux can be left on the assembly for days and still be able to remove with water. However, it is recommended to remove the post residue with the shorter delay time possible to achieve higher reliability and lowest possible ionic contamination level. For higher cleanliness contamination value, it is recommended to use DI water of minimum 5 mega ohm resistivity value at the final water-rinse.

PHYSICAL PROPERTIES

STORAGE

EIE 3118 flux is alcohol-based and is flammable. Store and keep away from sources of ignition.

PACKAGING

25 litre per carboy